

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (Currently Amended) A semiconductor device, comprising:
 - a first carrier substrate;
 - a first semiconductor chip mounted face down on the first carrier substrate;
 - a first anisotropic conductive sheet disposed between the first semiconductor chip and the first carrier substrate and having a first side and a second side, the first side of the first anisotropic conductive sheet being in contact with the first carrier substrate and a pair of lands and the second side of the first anisotropic conductive sheet having a first portion in contact with the first semiconductor chip and a second portion extending past the first semiconductor chip;
 - a second semiconductor chip mounted face down on a reverse face of the first carrier substrate;
 - a second anisotropic conductive sheet disposed between the second semiconductor chip and the first carrier substrate and having a first side and a second side, the first side of the second anisotropic conductive sheet being in contact with the first carrier substrate and a pair of lands and the second side of the second anisotropic conductive sheet having a first portion in contact with the second semiconductor chip and a second portion extending past the second semiconductor chip;
 - a second carrier substrate;
 - a third semiconductor chip mounted on the second carrier substrate; and
 - protruding electrodes connecting the second carrier substrate to the first carrier substrate so that the second carrier substrate is held above and spaced apart from the first semiconductor chip such that a gap is created between the second carrier substrate

and the first semiconductor chip and between second carrier substrate and the second portion of the first anisotropic conductive sheet;

wherein the third semiconductor chip comprises a structure in which a plurality of chips are stacked.

2. (Cancelled)

3. (Original) The semiconductor device according to Claim 1, further comprising a sealant for sealing the third semiconductor chip.

4. (Original) The semiconductor device according to Claim 3, wherein the sealant further comprises a molded resin.

5. (Original) The semiconductor device according to Claim 4, wherein a position of a sidewall of the sealant coincides with a sidewall of the second carrier substrate.

6-7. (Cancelled)

8. (Original) The semiconductor device according to Claim 1,
wherein the first carrier substrate on which the first semiconductor chip and the second semiconductor chip are mounted further comprises a flip-chip-mounted ball grid array, and

wherein the second carrier substrate on which the third semiconductor chip is mounted further comprises at least one of a mold-sealed ball grid array and a chip size package.

9. (Cancelled)

10. (Original) The semiconductor device according to Claim 1, wherein the third semiconductor chip comprises a structure in which a plurality of chips is arranged in parallel on the second carrier substrate.

11-17. (Cancelled)